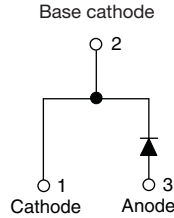
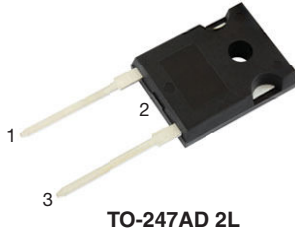


Hyperfast Soft Recovery Diode, 60 A FRED Pt[®] Gen 4


FEATURES

- Gen 4 FRED Pt[®] technology
- Low I_{RRM} and reverse recovery charge
- Very low forward voltage drop
- Polyimide passivated chip for high reliability standard
- 175 °C operating junction temperature
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



PRODUCT SUMMARY	
Package	TO-247AD 2L
$I_{F(AV)}$	60 A
V_R	600 V
V_F at I_F	1.48 V
t_{rr} typ.	see Recovery table
T_J max.	175 °C
Diode variation	Single die

DESCRIPTION

Gen 4 Fred technology, state of the art, ultralow V_F , soft switching optimized for Discontinuous (Critical) Mode (DCM) and IGBT F/W diode.

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	V_R		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 106$ °C	60	A
Single pulse forward current	I_{FSM}	$T_C = 25$ °C, $t_p = 8.3$ ms, half sine wave	425	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25$ °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100$ μ A	600	-	-	V
Forward voltage	V_F	$I_F = 50$ A	-	1.68	-	
		$I_F = 60$ A	-	1.75	2.0	
		$I_F = 50$ A, $T_J = 125$ °C	-	1.44	-	
		$I_F = 60$ A, $T_J = 125$ °C	-	1.55	-	
		$I_F = 50$ A, $T_J = 150$ °C	-	1.39	-	
		$I_F = 60$ A, $T_J = 150$ °C	-	1.48	1.65	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	-	50	μ A
		$T_J = 125$ °C, $V_R = V_R$ rated	-	-	500	
Junction capacitance	C_T	$V_R = 600$ V	-	30	-	pF



DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}$	$I_F = 60\text{ A}$ $di_F/dt = 1000\text{ A}/\mu\text{s}$ $V_R = 400\text{ V}$	-	68	-	ns
		$T_J = 125\text{ }^\circ\text{C}$		-	92	-	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^\circ\text{C}$		-	20	-	A
		$T_J = 125\text{ }^\circ\text{C}$		-	40	-	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^\circ\text{C}$		-	945	-	nC
		$T_J = 125\text{ }^\circ\text{C}$		-	2500	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	R_{thJC}		-	-	0.6	$^\circ\text{C}/\text{W}$
Thermal resistance, case to heat sink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5)	-	12 (20)	kgf · cm (lbf · in)
Marking device		Case style TO-247AD 2L	E4PH6006L			

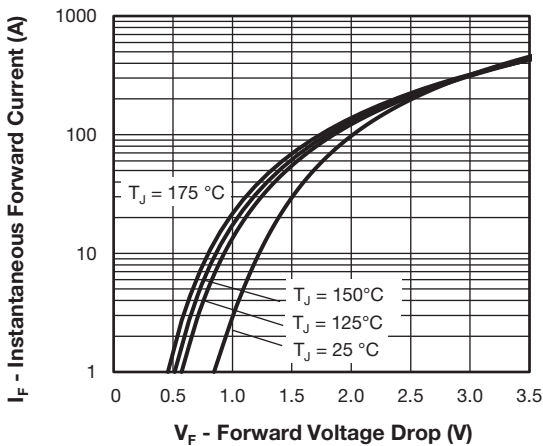


Fig. 1 - Typical Forward Voltage Drop Characteristics

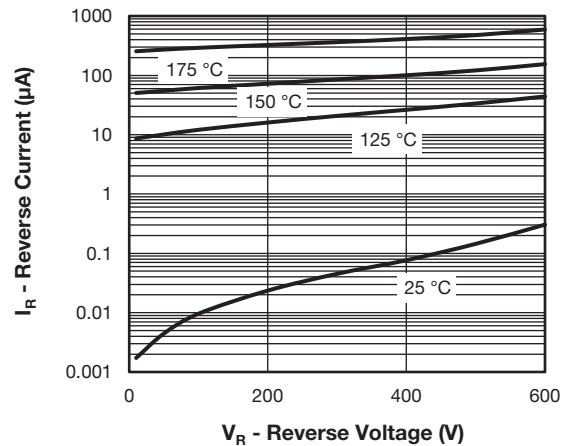


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

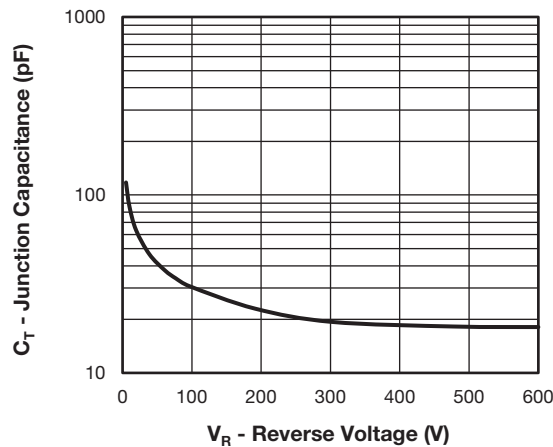


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

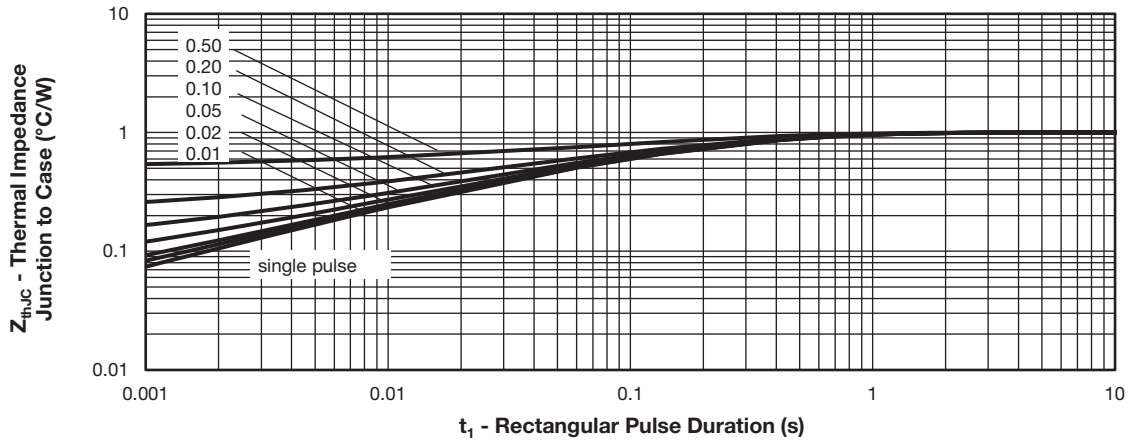


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

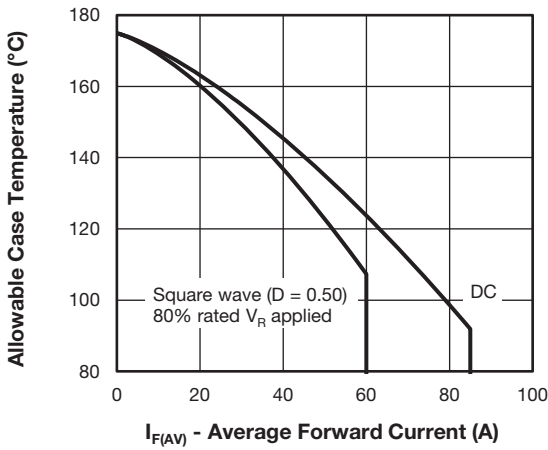


Fig. 5 - Max. Allowable Case Temperature vs. Average Forward Current

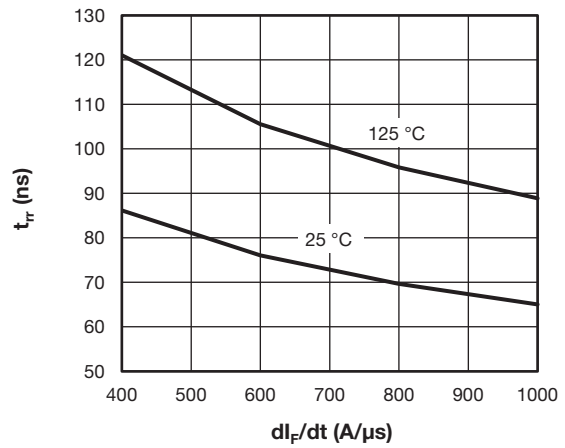


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

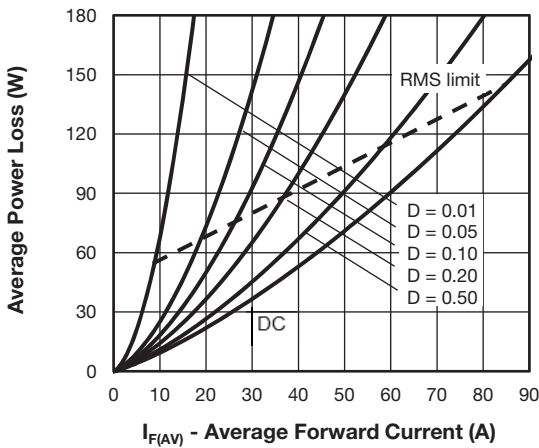


Fig. 6 - Forward Power Loss Characteristics

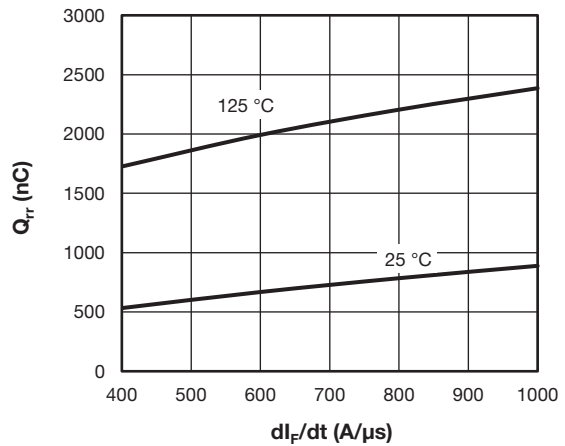


Fig. 8 - Typical Stored Charge vs. dI_F/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d(REV)}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see Fig.5)
 $P_{d(REV)}$ = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_R = rated V_R

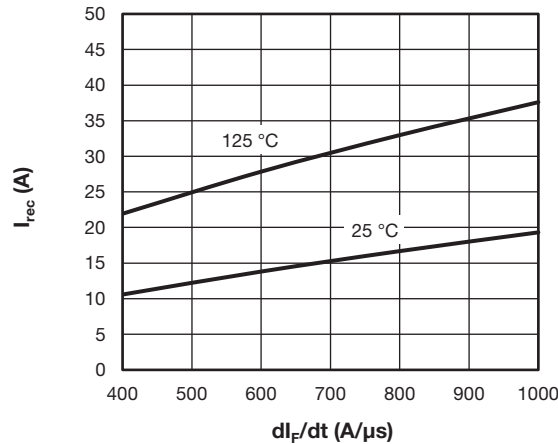


Fig. 9 - Typical Reverse Recovery vs. di_F/dt

ORDERING INFORMATION TABLE

Device code	VS-	E	4	P	H	60	06	L	-N3
	①	②	③	④	⑤	⑥	⑦	⑧	⑨

- 1** - Vishay Semiconductors product
- 2** - Circuit configuration:
E = single diode 2 pins
- 3** - FRED Gen 4
- 4** - P = TO-247 package
- 5** - Process type:
H = Hyperfast recovery
- 6** - Current rating (60 = 60 A)
- 7** - Voltage rating (06 = 600 V)
- 8** - L = long lead
- 9** - Environmental digit:
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

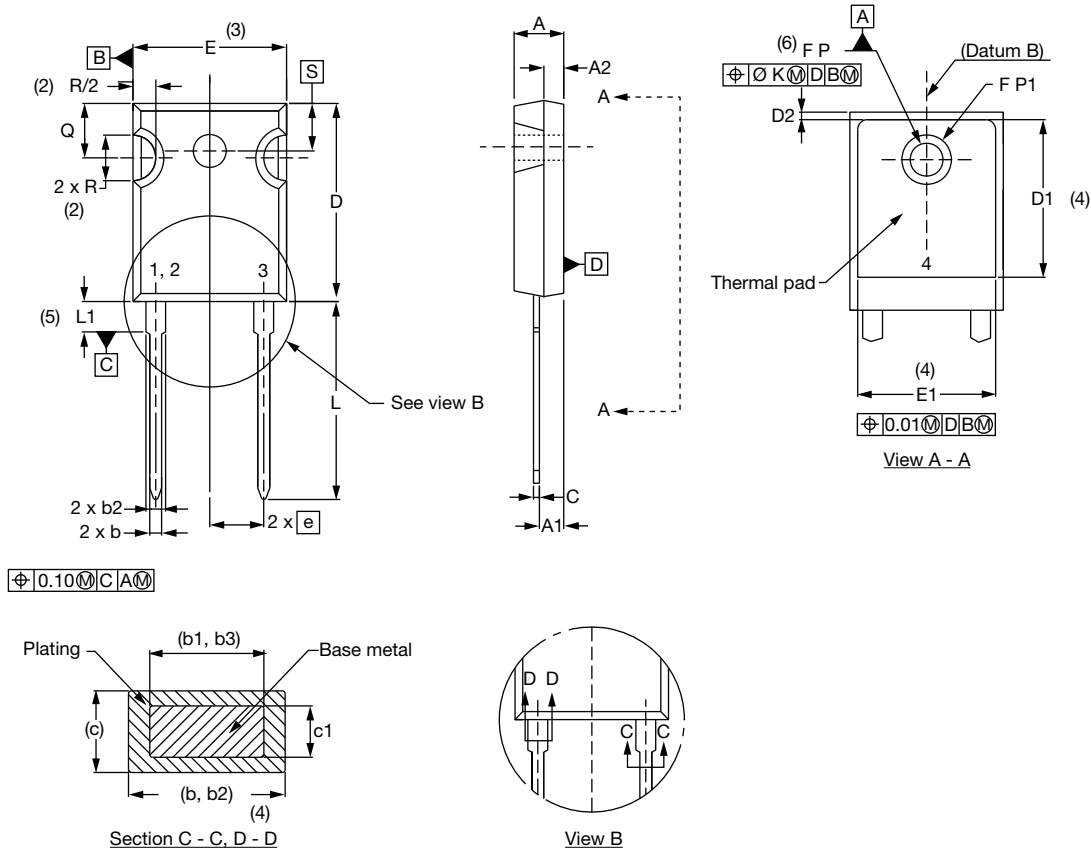
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-E4PH6006L-N3	25	500	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	TO-247AD 2L	www.vishay.com/doc?95536
Part marking information	TO-247AD 2L	www.vishay.com/doc?95648



TO-247AD 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209		E	15.29	15.87	0.602	0.625	3
A1	2.21	2.59	0.087	0.102		E1	13.46	-	0.53	-	
A2	1.50	2.49	0.059	0.098		e	5.46 BSC		0.215 BSC		
b	0.99	1.40	0.039	0.055		Ø K	0.254		0.010		
b1	0.99	1.35	0.039	0.053		L	19.81	20.32	0.780	0.800	
b2	1.65	2.39	0.065	0.094		L1	3.71	4.29	0.146	0.169	
b3	1.65	2.34	0.065	0.092		Ø P	3.56	3.66	0.14	0.144	
c	0.38	0.89	0.015	0.035		Ø P1	-	6.98	-	0.275	
c1	0.38	0.84	0.015	0.033		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4	S	5.51 BSC		0.217 BSC		
D2	0.51	1.35	0.020	0.053							

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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